

Title (en)
METHOD OF PRODUCING LASER-PROCESSED PRODUCT AND ADHESIVE SHEET, FOR LASER PROCESSING USED THEREFOR

Title (de)
VERFAHREN ZUR HERSTELLUNG EINES MIT EINEM LASER BEARBEITETEN PRODUKTS UND EINER DAFÜR VERWENDETEN KLEBEFOLIE ZUR LASERBEARBEITUNG

Title (fr)
METHODE DE PRODUCTION D'UN PRODUIT TRAITE PAR LASER ET D'UNE FEUILLE ADHESIVE, POUR UN TRAITEMENT LASER UTILISE POUR CE PRODUIT

Publication
EP 1634673 A4 20090408 (EN)

Application
EP 04728276 A 20040419

Priority

- JP 2004005554 W 20040419
- JP 2003120927 A 20030425
- JP 2003430093 A 20031225
- JP 2004095875 A 20040329
- JP 2004095785 A 20040329
- JP 2004094732 A 20040329
- JP 2004095492 A 20040329
- JP 2004094635 A 20040329
- JP 2004094431 A 20040329

Abstract (en)
[origin: EP1634673A1] A manufacturing method of laser processed parts is characterized in that at least a pressure-sensitive adhesive layer is provided on a base material as a pressure-sensitive adhesive sheet (2) for laser processing, using a material having specified physical properties, and this method comprises a step of adhering the pressure-sensitive adhesive sheet (2) for laser processing to the laser beam exit side of the work (1) by way of the pressure-sensitive adhesive layer, a step of processing the work by irradiating the work with a laser beam (6) of within 2 times of the irradiation intensity for forming a through-hole in the work (1), at higher than the irradiation intensity of threshold for inducing ablation of the work (1), and a step of peeling the pressure-sensitive adhesive sheet (2) for laser processing from the work (1) after the machining. Therefore, contamination of the work surface by decomposition products can be effectively suppressed, and laser processed parts can be manufactured easily and at high production efficiency.

IPC 8 full level
B23K 26/18 (2006.01); **C09J 7/02** (2006.01); **H01L 21/301** (2006.01); **H05K 3/00** (2006.01)

CPC (source: EP KR US)
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Citation (search report)

- [XDA] JP 2002343747 A 20021129 - LINTEC CORP
- [XDA] JP 2003034780 A 20030207 - FURUKAWA ELECTRIC CO LTD
- [AD] JP 2001118862 A 20010427 - NEC MACHINERY CORP & US 6561743 B1 20030513 - NAKATSU AKIRA [JP]
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